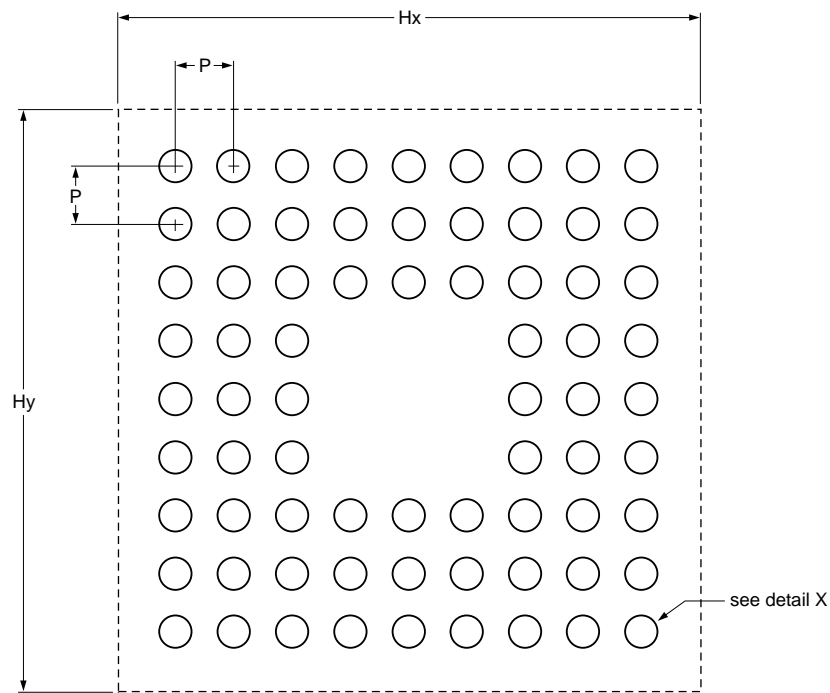







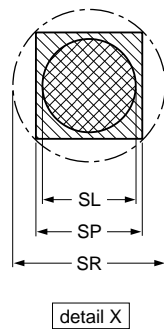
Footprint information for reflow soldering of LFBGA167 package

SOT836-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
-  occupied area
-  solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	14.400	14.400